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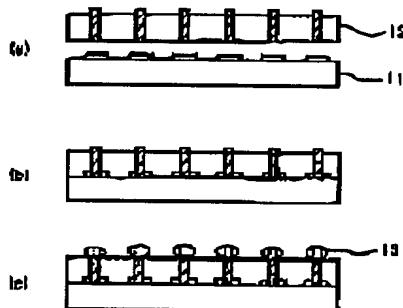
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(54) BALL GRID ARRAY TYPE PACKAGE AND MOUNTING STRUCTURE THEREFOR

(57) Abstract:

PURPOSE: To obtain a method for introducing a low elasticity elastomer for reducing thermal stress relatively easily into a semiconductor package structure having ball grid array structure.
 CONSTITUTION: In a semiconductor package structure having ball grid array terminals to be connected electrically with a mounting board, an elastomer 12 having interlayer connecting function is employed in the connection between a semiconductor element 11, and the ball grid array terminal thus relaxing thermal stress caused by the difference of coefficient of thermal expansion between the semiconductor element 11 and the mounting board.



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